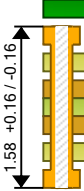







Layer	Stack up	Description	Type	Base Thickness	Finish Thickness	Mask Thickness	εr	Resin Content	Impedance ID	Data Filenames	
1		Soldermask	SolderMask			0.020	4.100				
		Foil	Foil	0.018	0.043				1, 2		
		EM-827B-2116	PREPREG	0.127	0.108		4.100	55.000			
		EM827B	Core	0.017	0.017		4.400	43.000			
		EM-827B-2116	PREPREG	1.200	1.200		4.100	55.000			
2		Foil	Foil	0.017	0.017						
3		EM-827B-2116	PREPREG	0.127	0.108		4.100	55.000			
4		Foil	Foil	0.018	0.043				3, 4		
		Soldermask	SolderMask			0.020	4.100				

Impedance ID	Structure Image	Structure Name	Impedance Signal Layer	Ref. Plane 2 in Layer	Ref. Plane 1 in Layer	Lower Trace Width (W1)	Trace Separation (S1)	Ground Strip Separation (D1)	Broadside 2nd Layer	Calculated Impedance	Target Impedance	Tol (+/- %)	CI Notes-1	
1		Coated Microstrip 1B	1	0	2	0.170	0.000	0.000	0	50.200	50.000	10.000		
2		Edge Coupled Coated Microstrip 1B	1	0	2	0.120	0.160	0.000	0	100.340	100.000	10.000		
3		Coated Microstrip 1B	4	0	3	0.170	0.000	0.000	0	50.200	50.000	10.000		
4		Edge Coupled Coated Microstrip 1B	4	0	3	0.120	0.160	0.000	0	100.340	100.000	10.000		

Column Position	Drill Image	1st Layer	2nd Layer	Drill Type	Minimum Size	Fill Type	Data Filenames	
1		1	4	Mechanical PTH	0.250	None		

Notes

StackName: NCI_Raspberry-Spider_4L_EM827	Version:	Revision:	Modification:	Date of Revision:	Editor	Page 1/1	
Date: 01/05/2018	Associated Documents:						
Author: Mostefa Abdali							
Department: IDS							
Site: Tewkesbury							